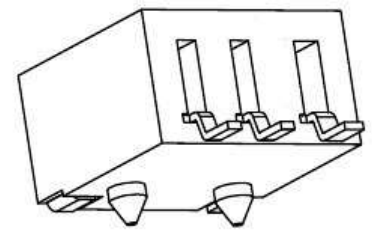
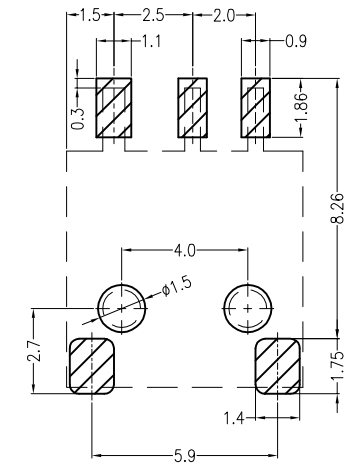
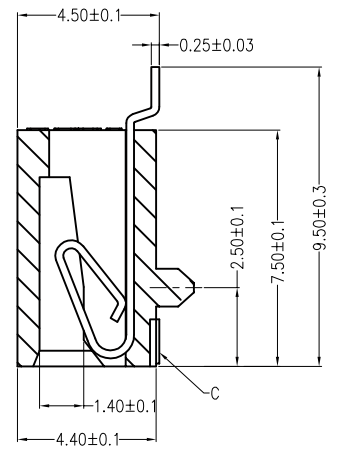
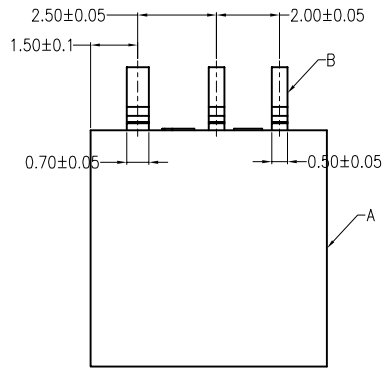
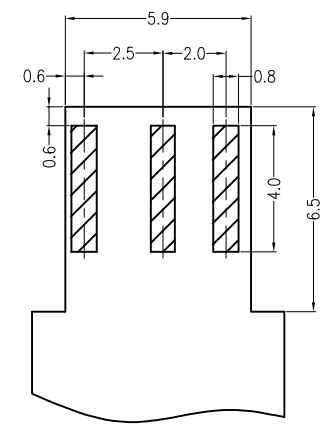
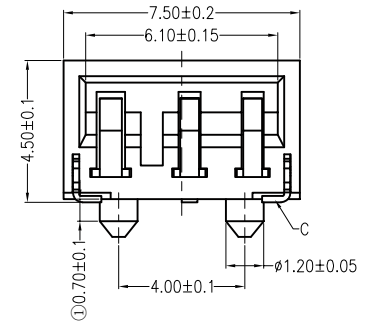


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30

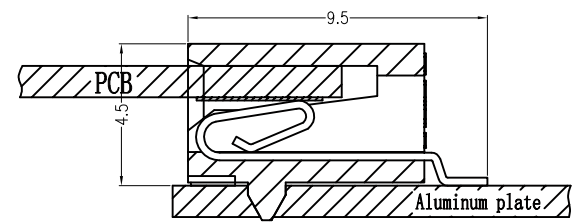


Board Layout

**Main Specifications**  
 Thickness: 1.0mm  
 Contact resistance:  $\leq 20\text{m}\Omega$   
 Insulation resistance:  $\geq 800\text{M}\Omega$   
 Rated voltage: 250/150V AC DC  
 Rated current: 1.0A AC DC  
 Withstand Voltage: 1500V AC/minute  
 Temperature Range: -25°C --- +105°C



Mating Aluminum plate detail



Assembly Layout

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	3 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

<b>LEDsconn</b>			TITLE: -- 2.5/2.0mmPITCH 90°WAFER SMT TYPE		
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:		
.X±0.3	.X±2°				
.XX±0.25	.XX±1°	APPD: 邵敬和	DWG NO.:		
--	--	CHKD: 田峰			
UNITS: mm		DR: 蒋建银	SCALE: 1 : 1	SHEET: 1 / 1	